

123-02**REWORKABLE POLYIMIDE BASED DIE ATTACH ADHESIVE**

DESCRIPTION: 123-02 is a silver loaded, reworkable, electrically conductive adhesive. This product features excellent adhesion to Kapton, Mylar, FR4 board, glass and a variety of other substrates. This product can be reworked at temperatures as low as 180°C. Some applications for 123-02 include, but are not limited to, MCM-C, L or D, PPGA, PBGA, Flip Chip/KGD and solder replacement on PC boards. 123-02 is also useful for attaching large expansion mismatched components. 123-02 may be applied by syringe dispensing, screen-printing and stenciling techniques.

TYPICAL PROPERTIES:

Viscosity (cps)	25,000-50,000
Filler	Silver
% Filler (cured)	90 min.
Volume Resistance, max. (Ω -cm)	0.00008
Sheet Resistivity, max. (Ω /sq./mil)	0.03
Solderable	No
Thermal conductivity (W/mk)	2.5
Useful Temperature Range (°C)	-55 to 180
Thermal Stability (°C)	Good to 220

SUGGESTED HANDLING & CURING: 123-02 is ready to use as supplied. Further thinning may be accomplished by adding small amounts of CMI Thinner #203. Prior to using, be certain to resuspend silver. Best properties, for most applications, result when cured for 10 minutes at 180°C. Good properties are obtained on a variety of substrates by curing at temperatures ranging from 50°C to 200°C. End user is advised to experimentally determine temperature and time best suited for individual applications.

STORAGE: Shelf life: 3 months at 25°C; or 6 months at 5°C; or 9 months at -10°C.

SAFETY & HANDLING: Use with adequate ventilation. Keep away from sparks and open flames. Avoid prolonged contact with skin and breathing of vapors. Wash with soap and water to remove from skin.